

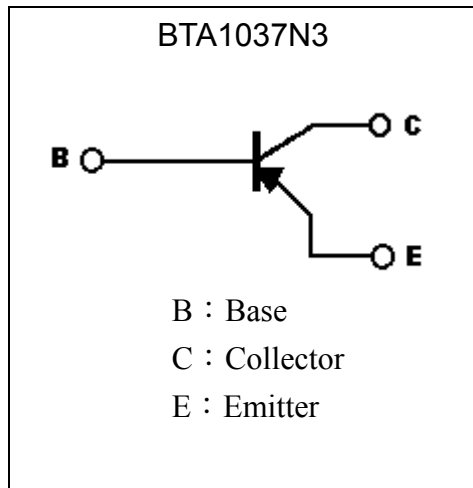
General Purpose PNP Epitaxial Planar Transistor

BTA1037N3

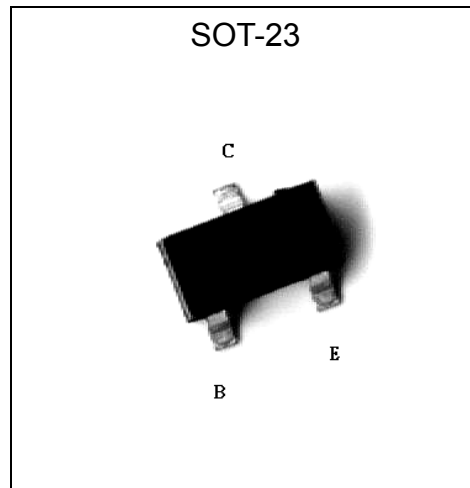
Description

- The BTA1037N3 is designed for using in driver stage of AF amplifier and general purpose amplification.
- Excellent h_{FE} linearity
- Complementary to BTC2412N3.
- Pb-free lead plating and halogen-free package

Symbol

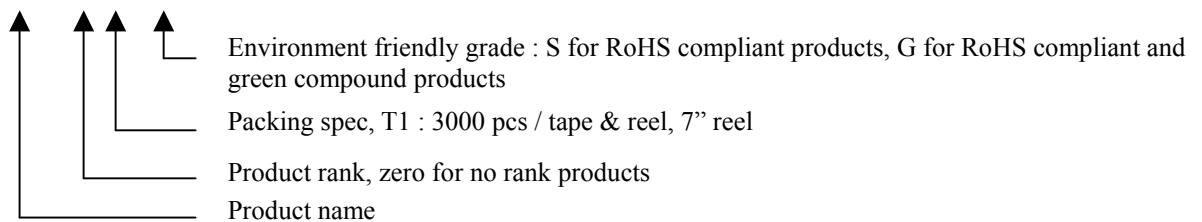


Outline



Ordering Information

Device	Package	Shipping
BTA1037N3-X-T1-G	SOT-23 (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel



**Absolute Maximum Ratings** (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CB0}	-100	V
Collector-Emitter Voltage	V _{CEO}	-65	V
Emitter-Base Voltage	V _{EB0}	-6	V
Collector Current	I _C	-150	mA
Power Dissipation	P _D	225	mW
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55~+150	°C

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	-100	-	-	V	I _C =-50μA
BV _{CEO}	-65	-	-	V	I _C =-1mA
BV _{EB0}	-6	-	-	V	I _E =-50μA
I _{CB0}	-	-	-0.1	μA	V _{CB} =-80V
I _{EB0}	-	-	-0.1	μA	V _{EB} =-6V
*V _{CE(sat)}	-	-0.12	-0.3	V	I _C =-50mA, I _B =-5mA
*V _{CE(sat)}	-	-0.06	-0.2	V	I _C =-10mA, I _B =-0.5mA
*V _{CE(sat)}	-	-0.25	-0.5	V	I _C =-100mA, I _B =-5mA
*V _{BE(sat)}	-	-0.75	-0.9	V	I _C =-10mA, I _B =-0.5mA
*V _{BE(sat)}	-	-0.92	-1.2	V	I _C =-100mA, I _B =-5mA
*V _{BE(on)}	-600	-	-750	mV	V _{CE} =-6V, I _C =-2mA
*V _{BE(on)}	-	-	-820	mV	V _{CE} =-6V, I _C =-10mA
*h _{FE}	180	-	820	-	V _{CE} =-6V, I _C =-1mA
f _T	100	160	-	MHz	V _{CE} =-12V, I _C =-2mA, f=30MHz
C _{ob}	-	4.0	5.0	pF	V _{CB} =-12V, f=1MHz

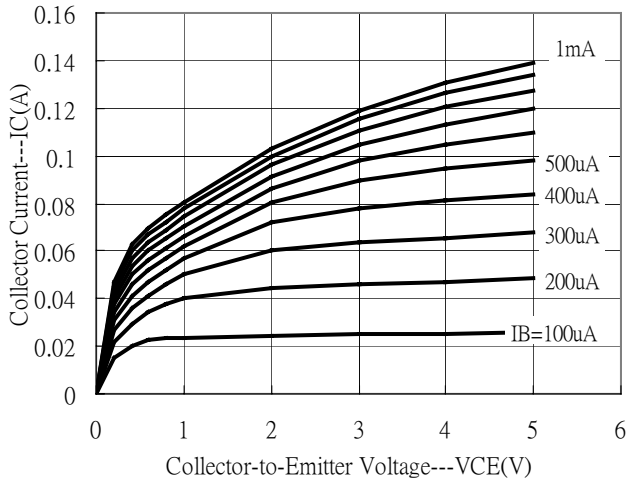
*Pulse Test: Pulse Width ≤380μs, Duty Cycle ≤2%

Classification Of h_{FE}

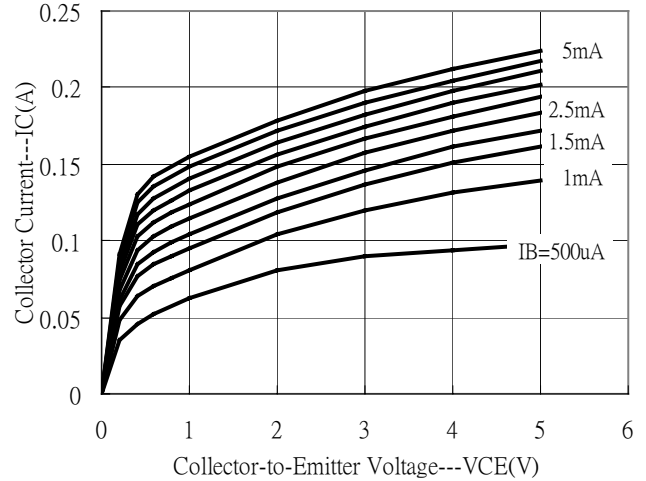
Rank	R	S	T
Range	180~390	270~560	390~820

Typical Characteristics

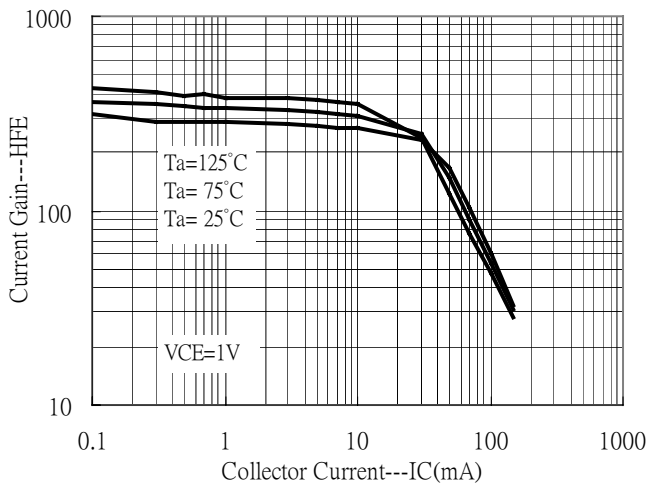
Emitter Grounded Output Characteristics



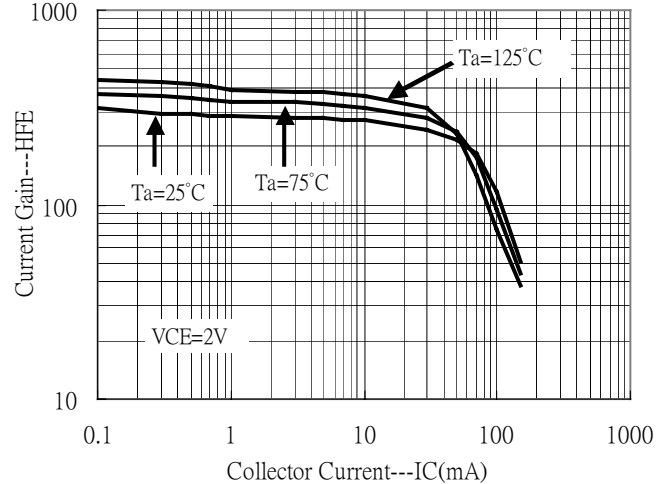
Emitter Grounded Output Characteristics



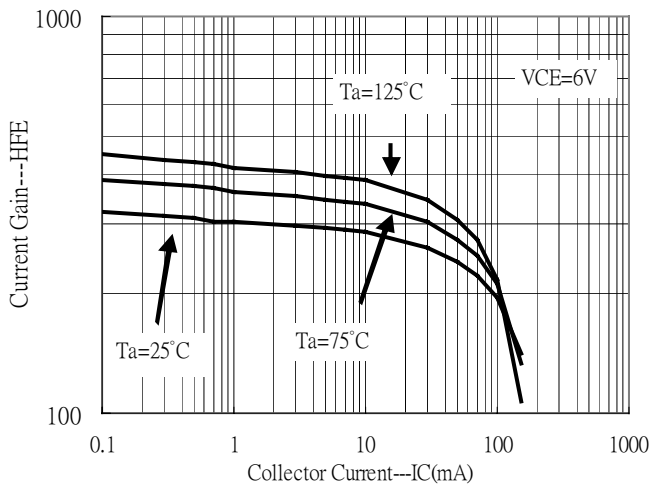
Current Gain vs Collector Current



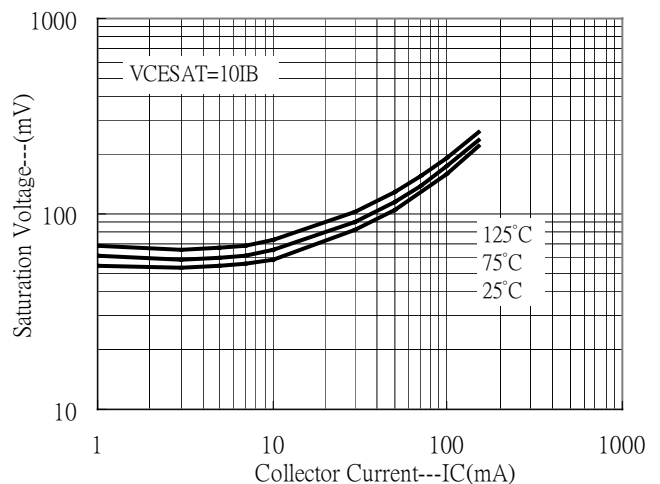
Current Gain vs Collector Current



Current Gain vs Collector Current

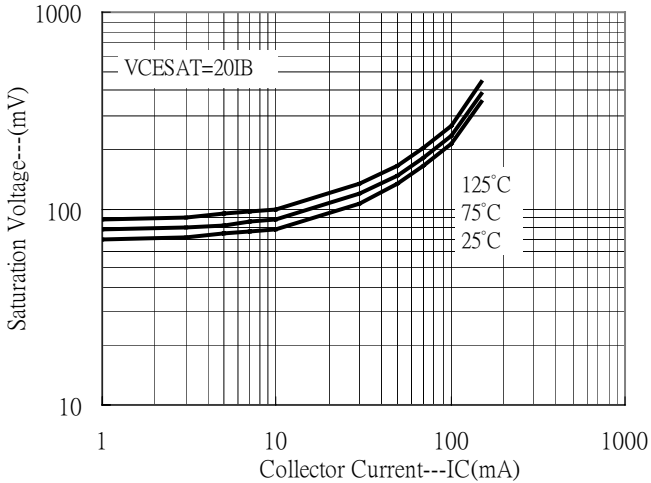


Saturation Voltage vs Collector Current

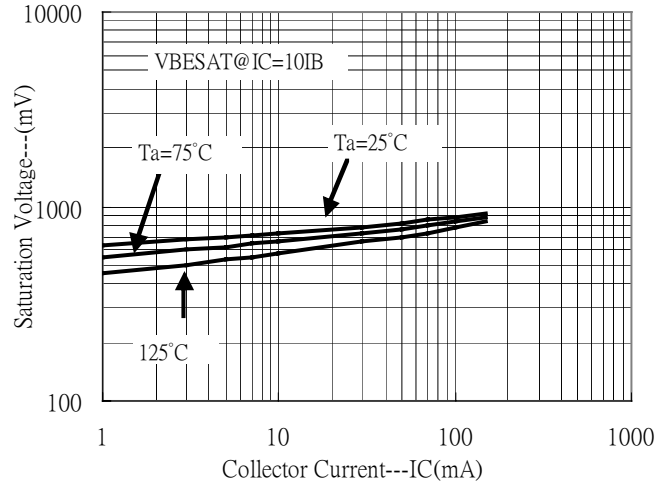


Typical Characteristics(Cont.)

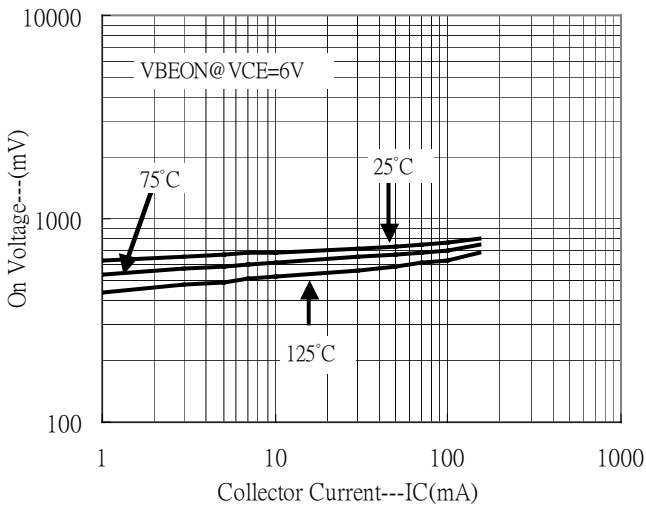
Saturation Voltage vs Collector Current



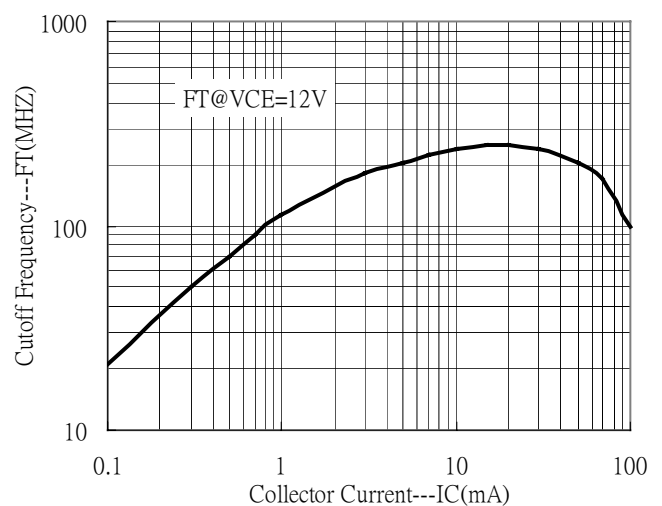
Saturation Voltage vs Collector Current



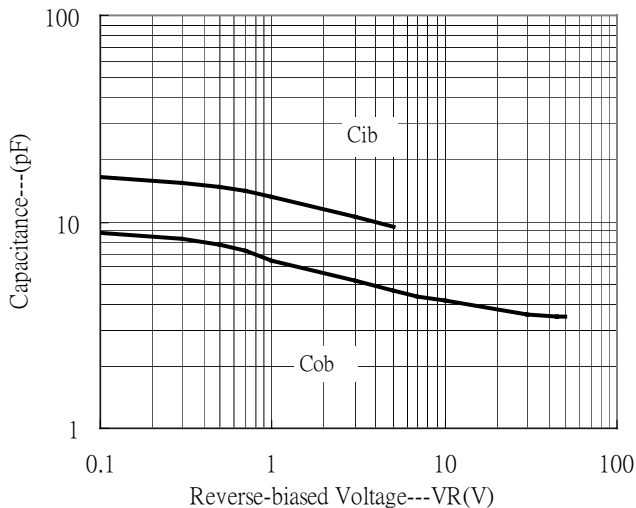
On Voltage vs Collector Current



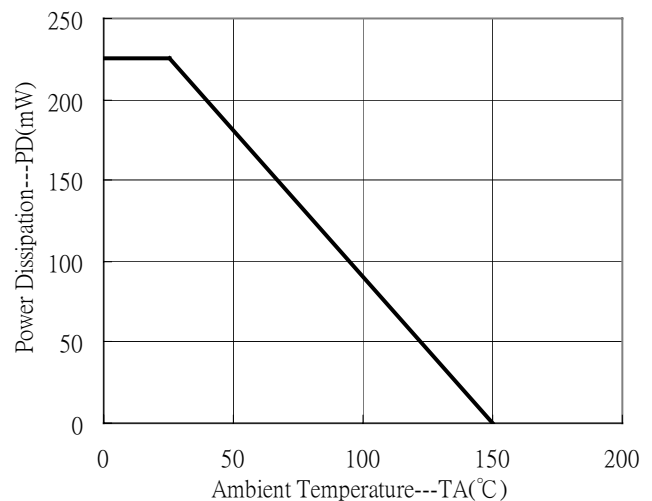
Cutoff Frequency vs Collector Current



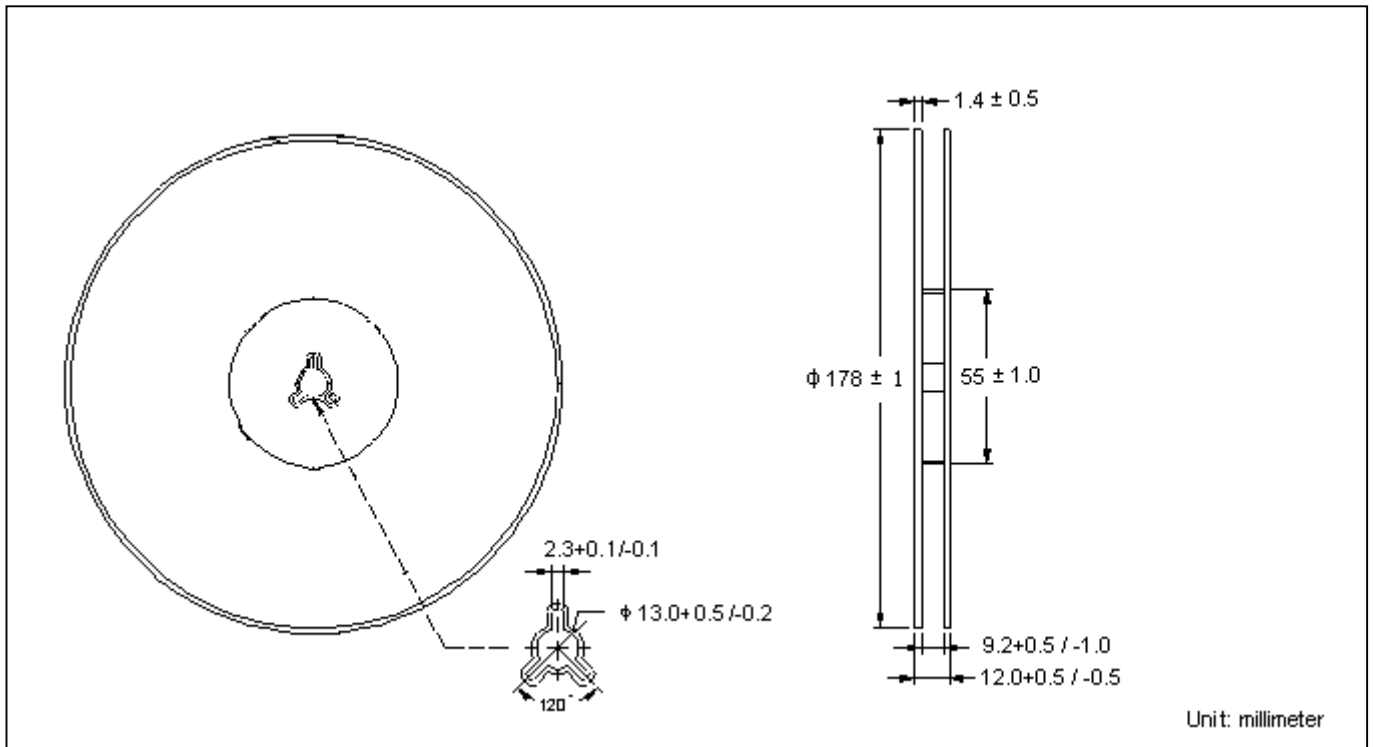
Capacitance vs Reverse-biased Voltage



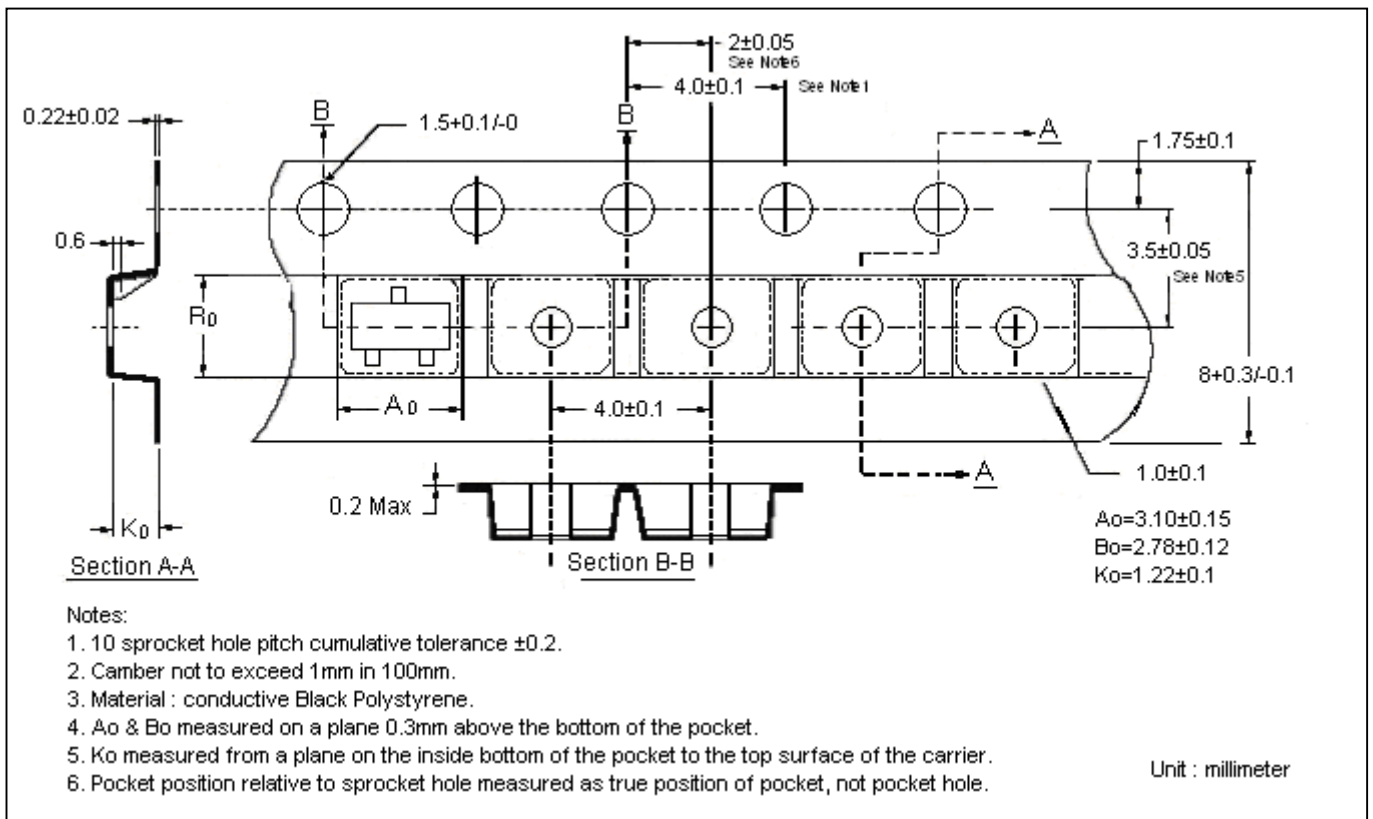
Power Derating Curve



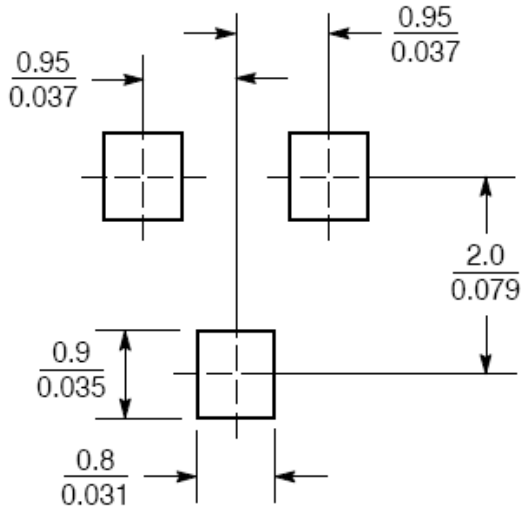
Reel Dimension



Carrier Tape Dimension



Recommended Soldering Footprint

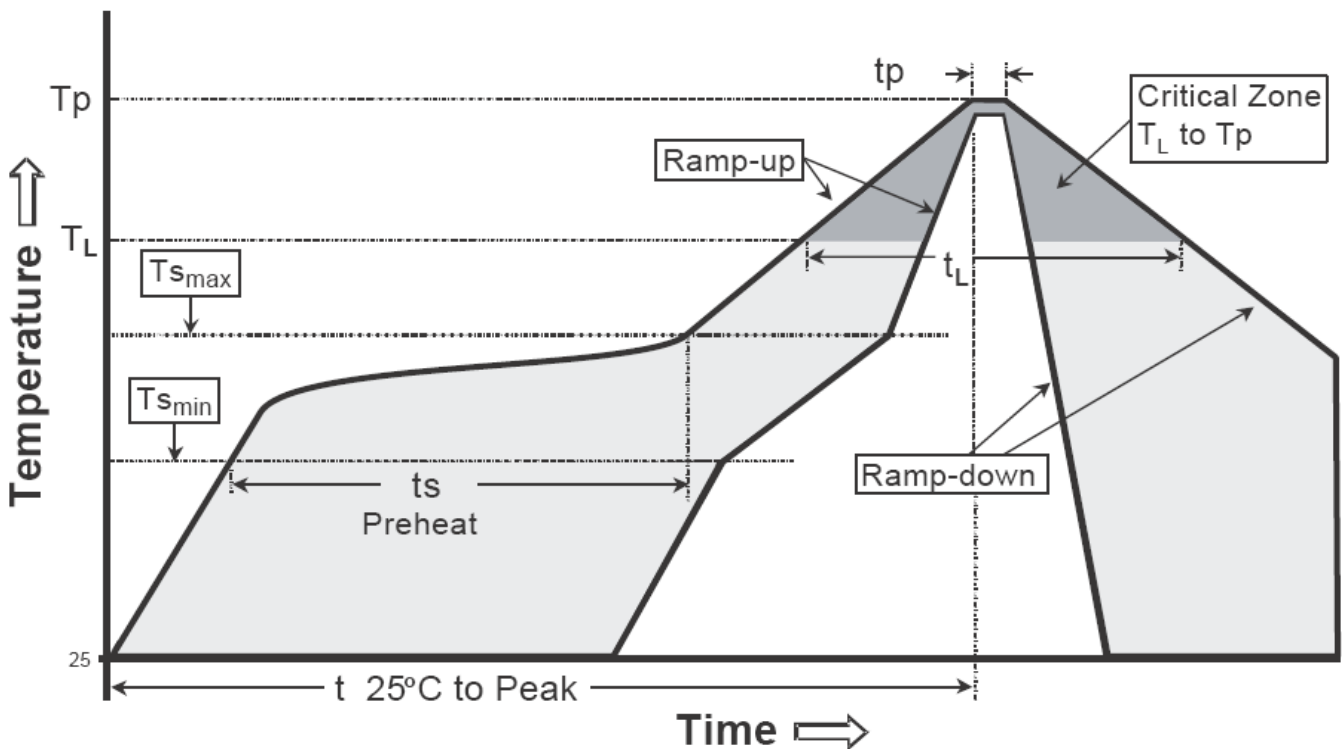


Unit : $\frac{\text{mm}}{\text{inches}}$

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

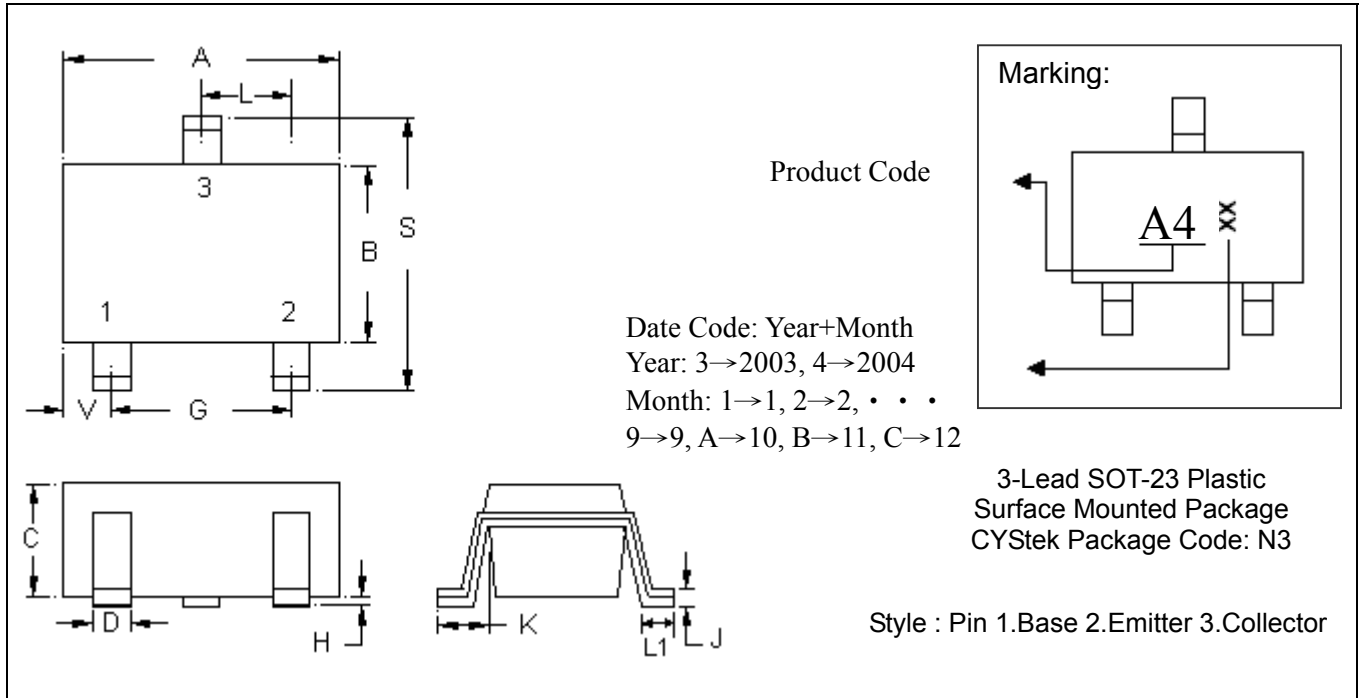
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-23 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0032	0.0079	0.08	0.20
B	0.0472	0.0669	1.20	1.70	K	0.0118	0.0266	0.30	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1161	2.10	2.95
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0000	0.0040	0.00	0.10	L1	0.0118	0.0197	0.30	0.50

Notes : 1.Controlling dimension : millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : Pure tin plated..
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0.

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